

ABSTRACT

MULTILAYER SUBSTRATE FOR A BUILDUP WITH A VIA, AND
METHOD FOR PRODUCING THE SAME

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A multilayer substrate for a buildup with a via,
which multilayer substrate comprises a base material
comprising an insulation resin layer on which a
predetermined hole is formed,

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wherein an electrodeposition layer is formed by
circular oscillation electroplating on the inside wall
surface of the hole and on the predetermined surface of
the insulation resin layer,

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the electrodeposition layer on the inside wall
surface of the hole being formed in a thickness greater
than the electrodeposition layer formed on the surface of
the insulation resin layer and a method for the production
of the substrate.